In the Claims

1. (Cancelled)

2. (Previously Amended) The embossing surface of claim 1, wherein said polyimide is aqueous developable.

3. (Canceled)

4. (Currently Amended) The embossing surface of claim 31, wherein said data is text.

5. (Currently Amended) The embossing surface of claim 31, wherein said data is image data.

6. (Currently Amended) The embossing surface of claim ~~3~~ 31, wherein said polyimide material is hardened by baking.

7. (Canceled)

8. (Currently Amended) The embossing surface of claim ~~7~~ 31, further comprising a flash-coated metal film over said polyimide material.

9. (Original) The embossing surface of claim 8, wherein said embossing surface is suitable for gravure printing.

10. (Currently Amended) A method of embossing data from a seamless embossing surface to other surfaces, said method ~~consisting of~~ comprising the steps of:

(a) providing the seamless embossing surface made of a polyimide;

~~(a)~~ (b) profiling ~~exposing a~~ said polyimide ~~to~~ by EMF radiation to define ~~defining~~ said data;

~~(b)~~ (c) curing said polyimide with the data to achieve ~~an embossing surface of~~ a selected hardness; and

~~(c)~~ (d) using ~~said embossing surface~~ said polyimide with said data to emboss said data onto said other surfaces.

11. (Currently Amended) The method of claim 10, wherein step ~~(a)~~ (b) comprises a subsequent substep of:

(i) developing said polyimide with a solvent.

12. (Currently Amended) A method of claim 11, wherein ~~step (a), further comprises a preliminary substep of:~~

providing the seamless embossing surface in step (a) comprises applying said polyimide to a roller.

13. (Currently Amended) The method of claim 12, wherein step ~~(a)~~ (b) further comprises a preliminary substep of:

(iii) pre-curing said polyimide by heating.

14. (Canceled)

15. (Previously Amended) The method of claim 10, wherein step (b) of curing comprises heating said polyimide.

16. (Original) The method of claim 10, wherein said EMF radiation comprises light.

17. (Original) The method of claim 16, wherein said light is monochromatic and generated by a laser.

18. (Currently Amended) The method of claim 10, wherein step ~~(b)~~ (c) comprises a preliminary substep of:

applying a coating of metal over said polyimide.

19.(Currently Amended) The method of claim 18, wherein said step ~~(c)~~ (d) of using said seamless embossing surface to emboss said data is carried out as gravure printing on said other surfaces.

20. (Canceled)

21. (Canceled)

22. (Original) The method of claim 10, wherein said data is selected from a group consisting of images, printed text, reliefs and holograms.

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23. (Original) The method of claim 22, wherein said data is in a holographic dot matrix format.

24. (Original) The method of claim 10, wherein said polyimide is applied to a flat surface.

25. (Canceled)

26. (Currently Amended) A method of transferring data from a first surface to other surfaces via a transfer medium comprising a polyimide material, said method comprising the steps of:

(a) casting said transfer medium on a surface containing said data, wherein said casting includes separating said transfer medium from said surface containing said data such that said transfer medium includes said data; and,

(b) using said transfer medium to transfer said data to said other surfaces.

27. (Canceled)

28. (Currently Amended) A method of embossing data from a seamless embossing surface to other surfaces, said method comprising the steps of:

(a) curing a polyimide material to form said seamless embossing surface;

(b) ~~exposing~~ profiling said seamless embossing surface ~~to~~ by EMF radiation ~~defining~~ to define said data; ~~and~~

(c) developing said data on said seamless embossing surface by using a solution; and

(d) contacting said other surfaces by ~~applying~~ said seamless embossing surface to transfer data ~~to said other surfaces~~.

29. (Currently Amended) A method of transferring data from a first seamless surface to other surfaces, said method comprising the steps of:

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(a) curing a polyimide material to form said first seamless surface;

(b) ~~exposing~~ profiling said first seamless surface ~~to be profiled~~ by an external manipulation ~~corresponding to~~ to define said data; ~~and,~~

(c) developing said data on said first seamless surface with a solution; and

~~(c)~~ (d) ~~applying~~ contacting said other surfaces by said first seamless surface to apply said data to said other surfaces.

30. (Previously Amended) The method of claim ~~29~~ 28 wherein step ~~(c)~~ (d) of ~~applying~~ contacting said other surfacec by said ~~first~~ seamless embossing surface comprises ~~a~~ printing ~~operating~~ operation wherein ink is forced onto the other surfaces.

31 (New) A seamless embossing surface made of a photoprofilable polyimide material, the seamless embossing surface being disposed on a roller and comprising data profiled in the polyimide material by two interfering laser beams, wherein the polyimide material is wet developed to define the data on the seamless embossing surface.

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